

### ABSTRACT OF THE INVENTION

A vacuum debris removal system for an integrated circuit manufacturing device is disclosed. The vacuum debris removal system comprises at least one vacuum tube. An opening is formed in the at least one vacuum tube at a selected  
5 location to cause air flow away from an element of the integrated circuit manufacturing device.

"Express Mail" mailing label number: EV298565795US  
Date of Deposit: October 24, 2003  
This paper or fee is being deposited on the date indicated above with  
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